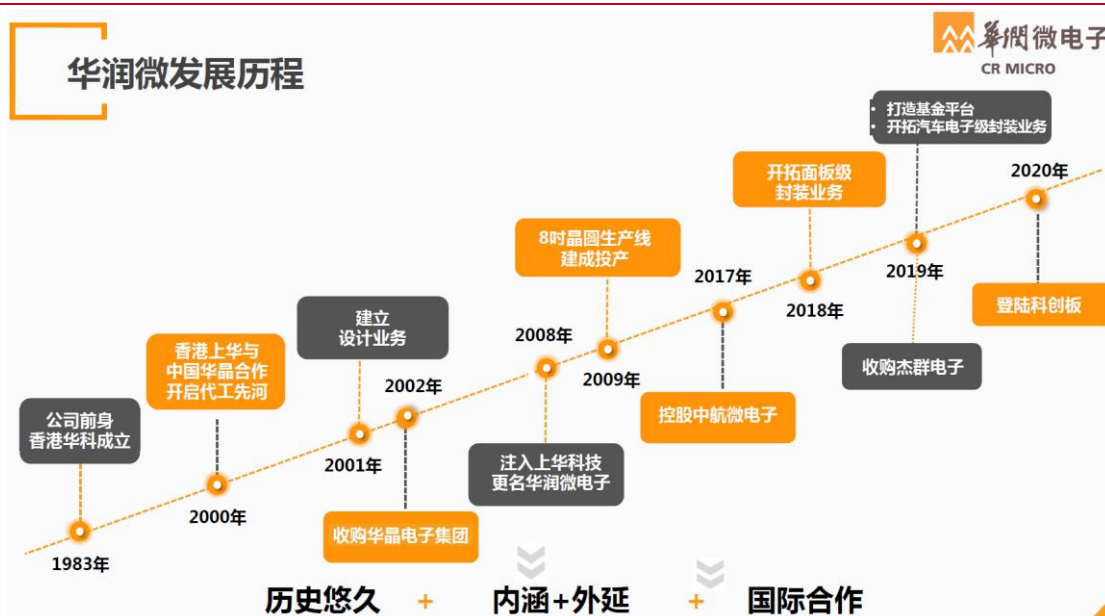


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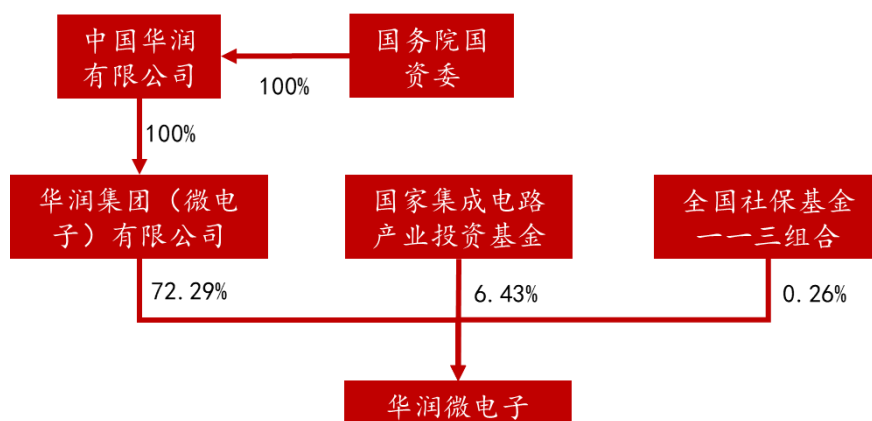
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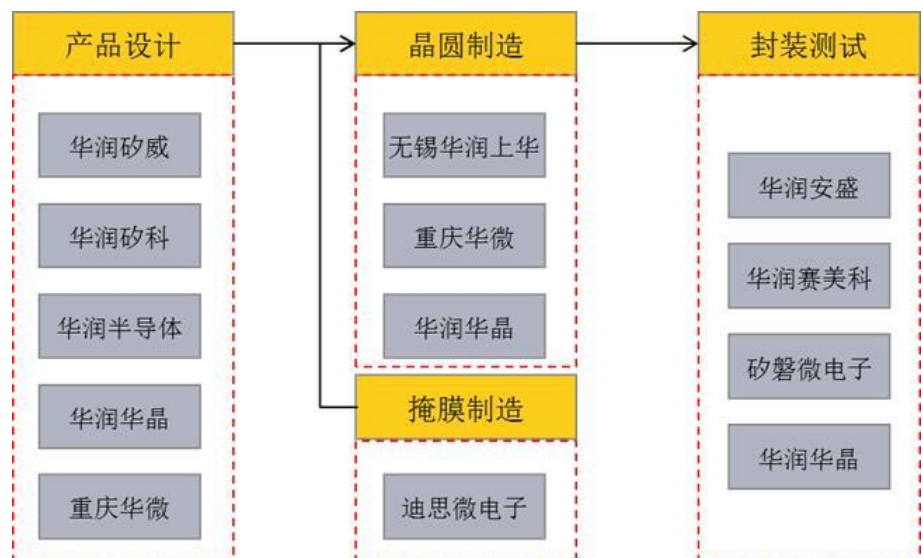
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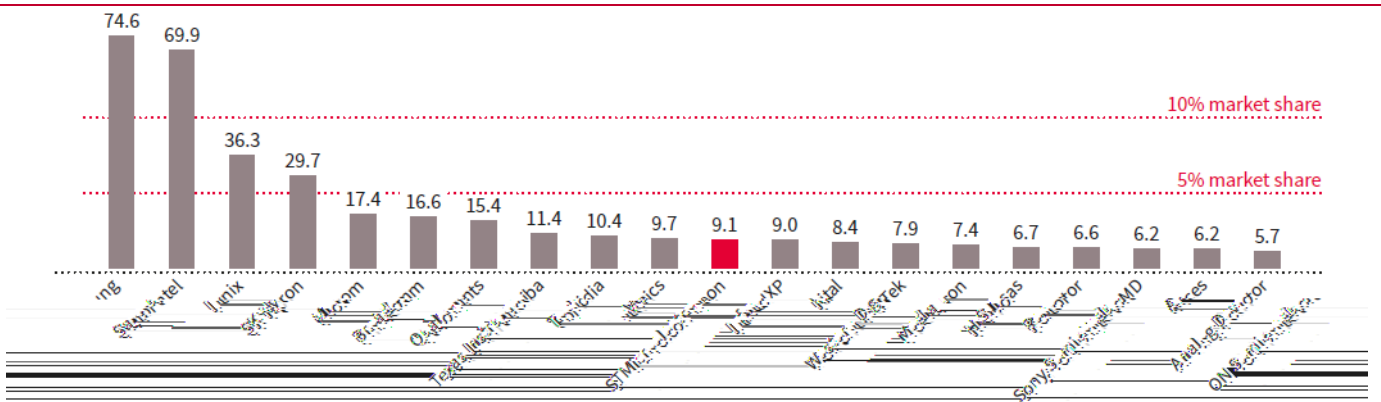
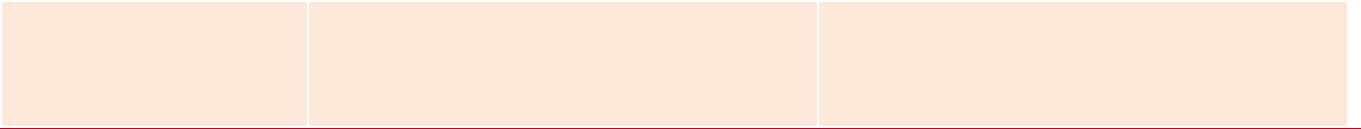


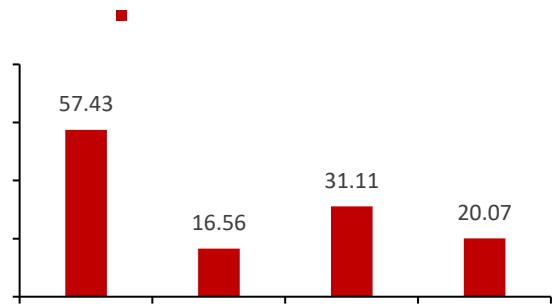
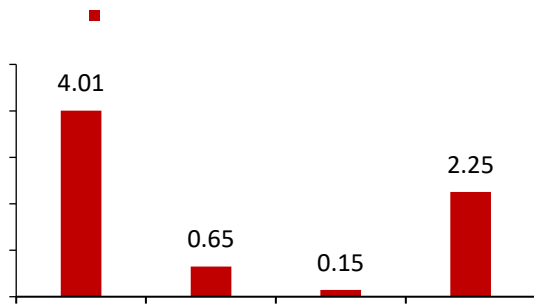
华润集团：五大业务战略组合



1.2.







1.3.



μ

■ 晶圆制造
提供性价比的6+8代工服务
中国排名前三本土晶圆制造企业



■ 掩模制造
中国生产光掩模产品的主要有四家，2018年华润微掩模市占率排名第一
中国四大本土掩模制造企业之一



■ 封装测试
公司具有完备的半导体封装生产工艺及模拟、数字、混合信号等多类导体测试生产工艺





多样化的封装形式

中测-封装-测试-烧录一站式服务

高精稳定的三温测试

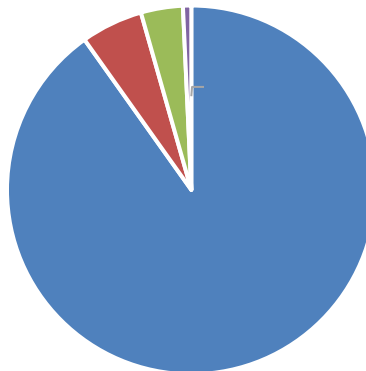
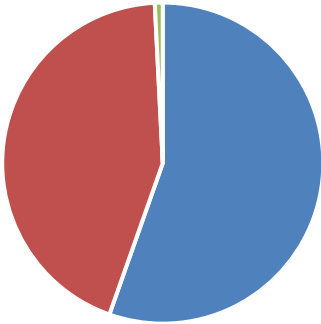
提供具有竞争力的特色模拟晶圆代工平台

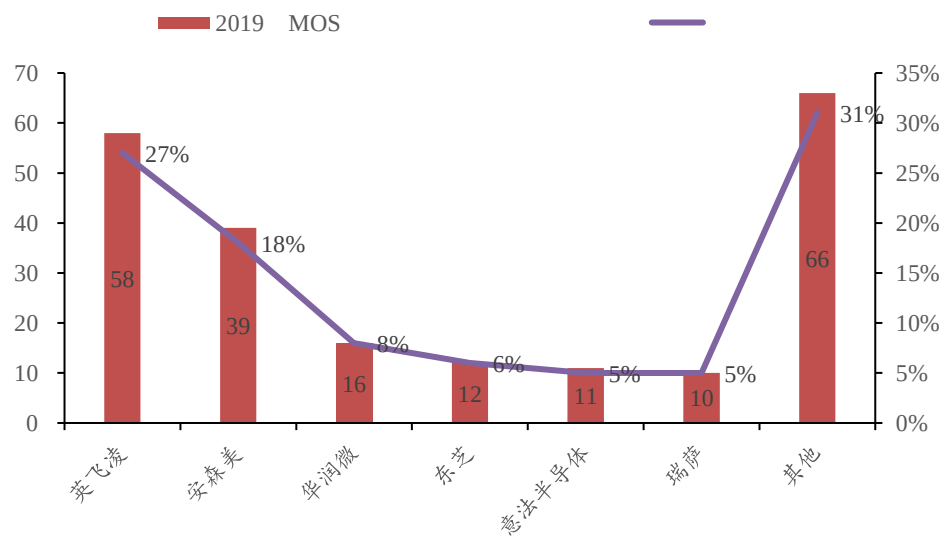
- 大硅片推出超高压1.0/0.8μm700V 8CD工艺平台并率先量产
- 国内首家超高压SOI工艺平台规模化生产线
- 国内领先的MEMS代工生产线
- 提供国内独有特色的200V/600V HVIC代工平台，用于电机驱动、智能功率模块等产品

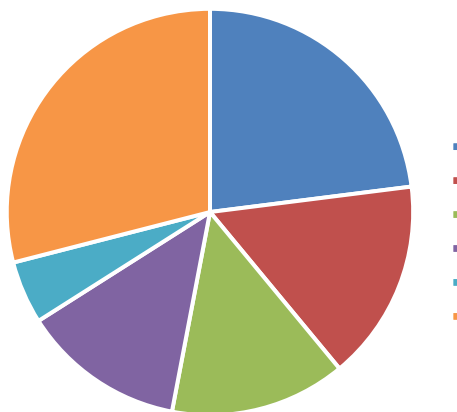
晶圆封装	封装形式	封装形式	封装形式
QFN	FC-QFN	FC-SOP	扇形阵列封装
TSOP	SSOP	LQFP	BGA
MSOP	TSOT	SOP	LGA

金线技术 **铜线 & 合金线技术** **Flip chip技术**

特殊封装	特殊封装	特殊封装	特殊封装
PMH-LF接插 DIP28 DIP28	PMH-DS接插 DIP24 DIP28	PMH-DS接插 DIP27 DIP32	QFN-QFN
Cooper Clip	光敏封装	100μm 12μm	CSP







FY 2019 Revenue: € 8,029 m

Digital Security Solutions



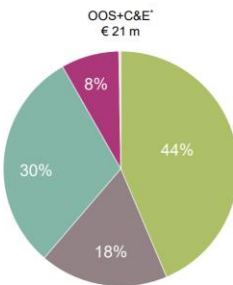
€ 642 m

Power & Sensor Systems



€ 2,445 m

* Other Operating Segments; Corporate & Eliminations



Automotive



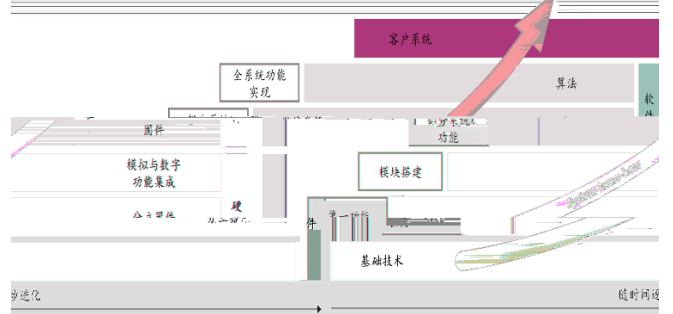
€ 3,503 m

Industrial Power Control



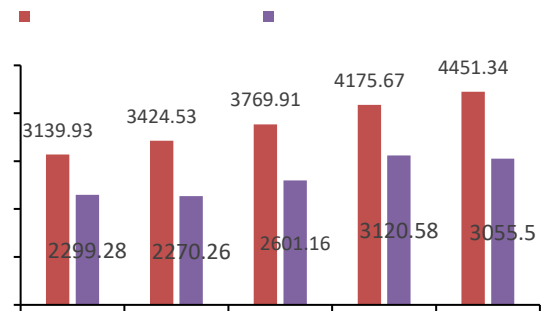
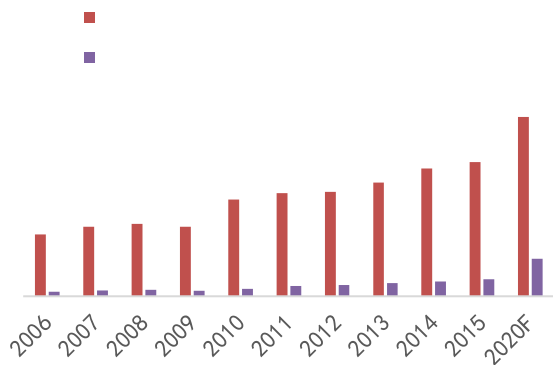
€ 1,418 m

System know-how is bridging the gap between core technology and target application

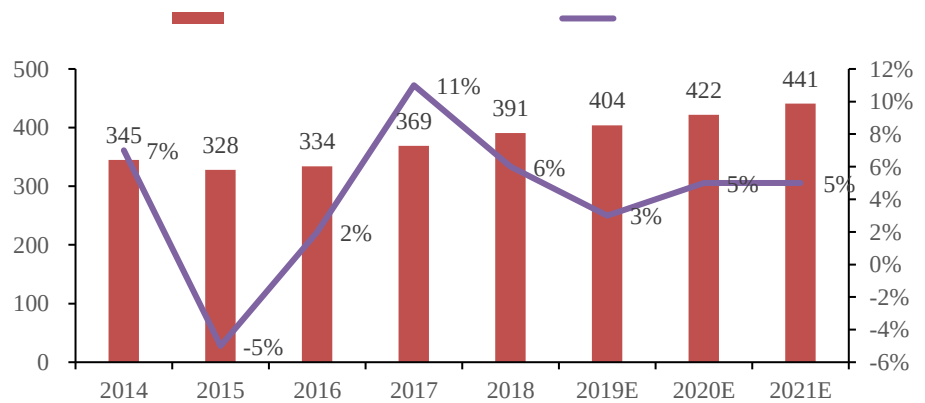


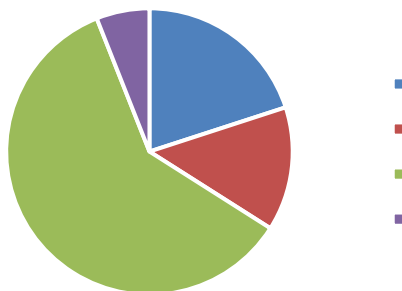
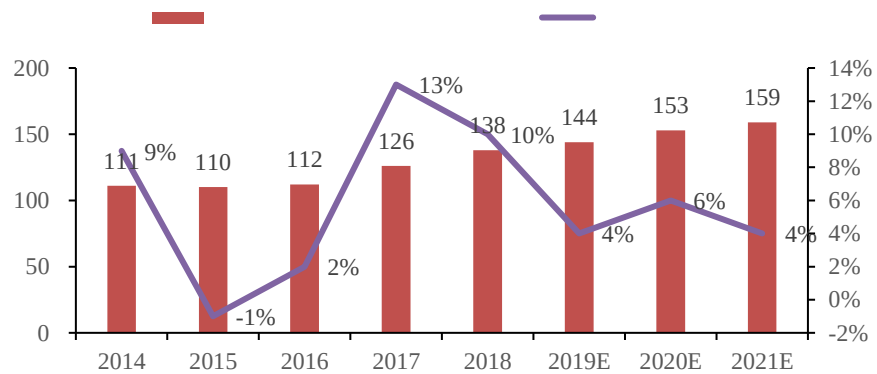
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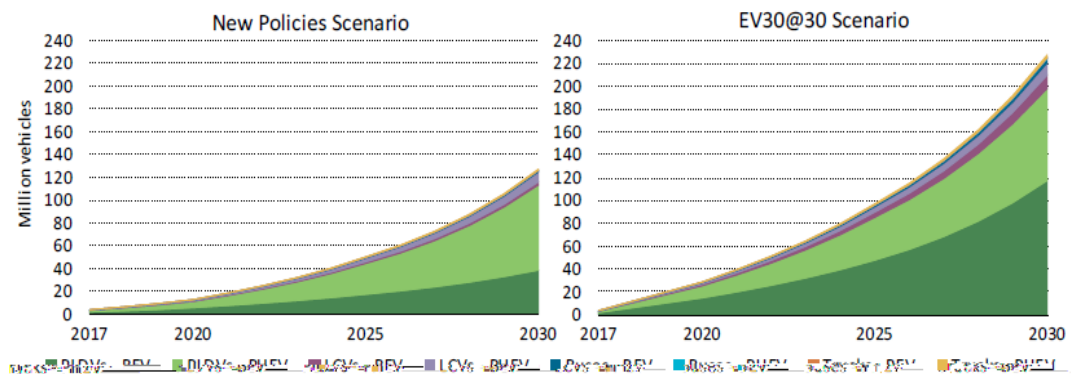
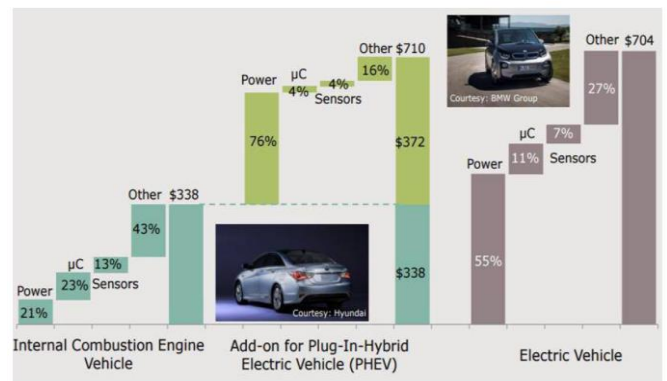
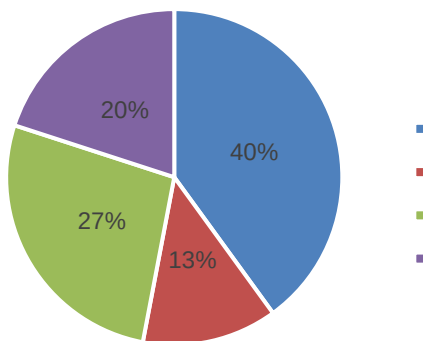
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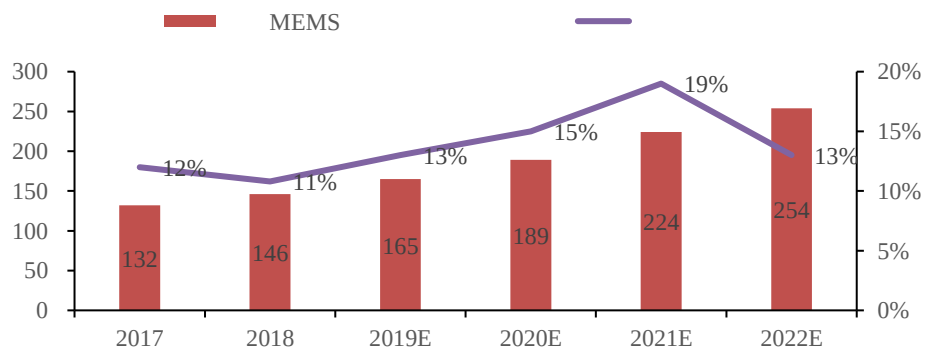
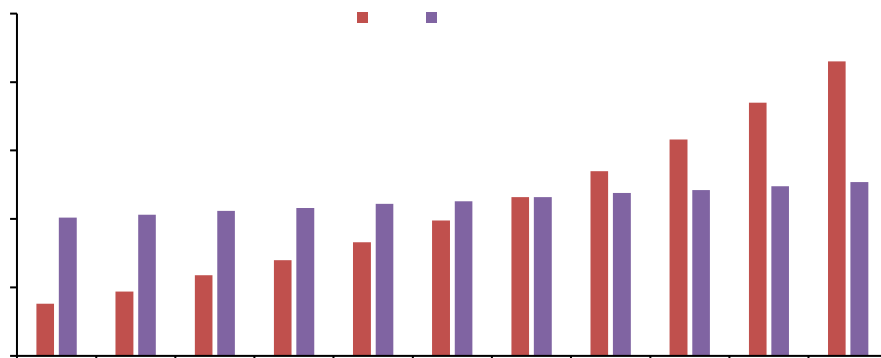


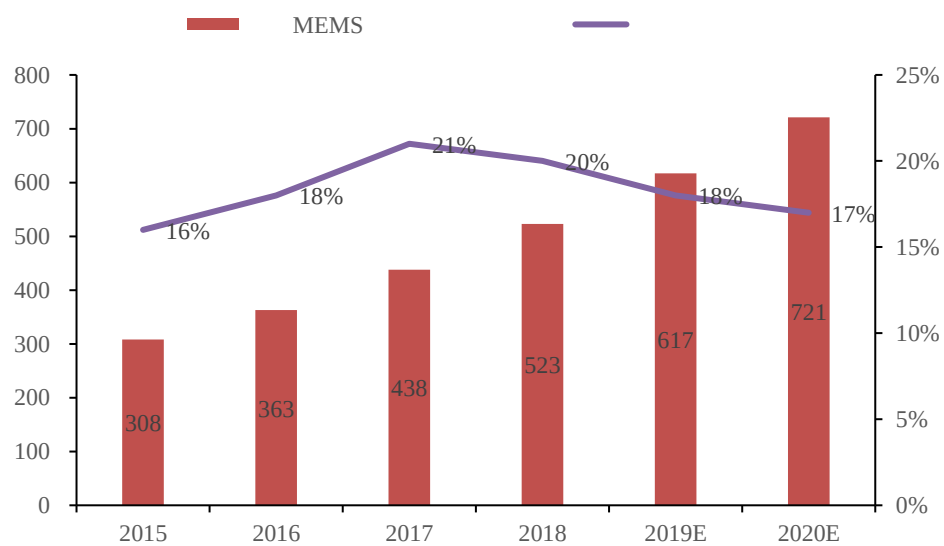
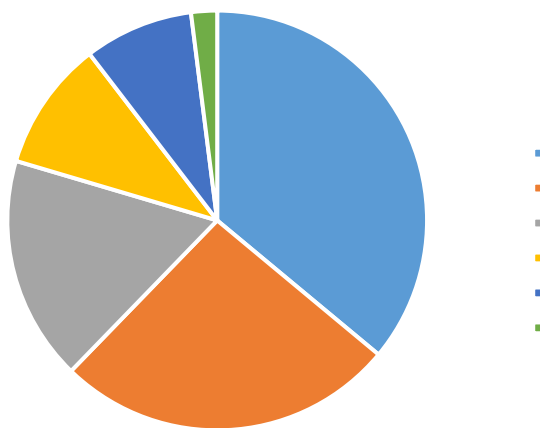
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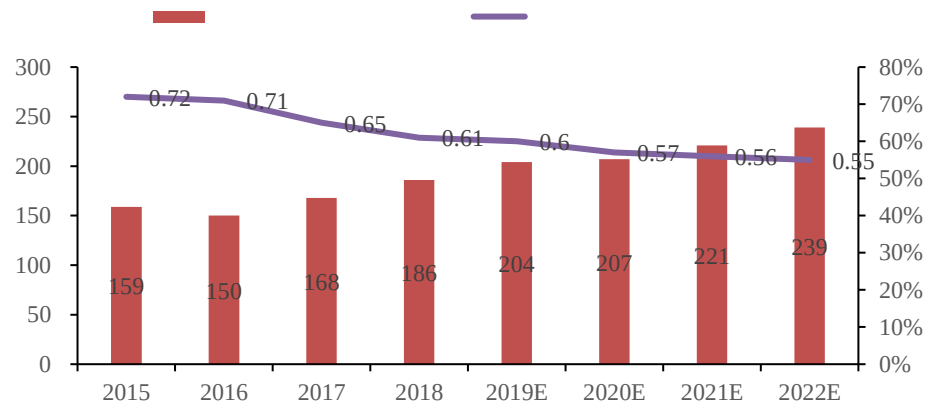


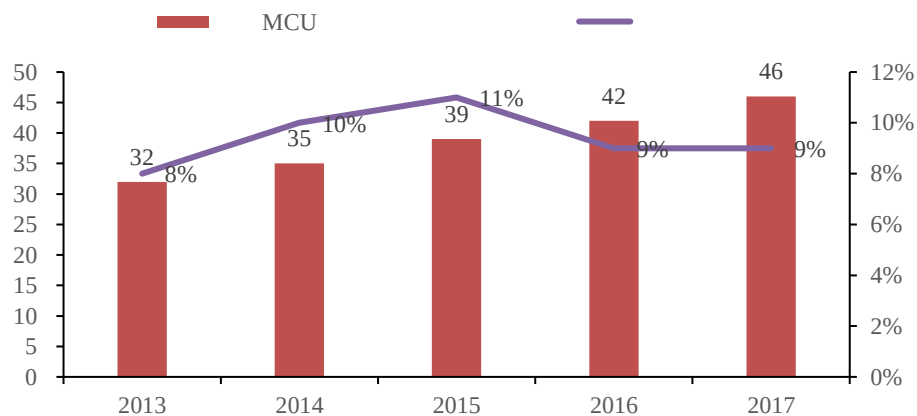




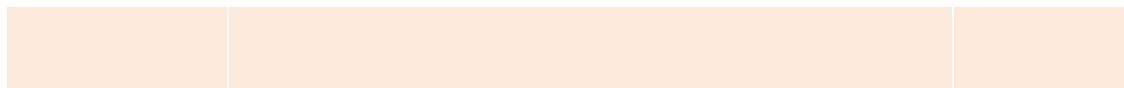


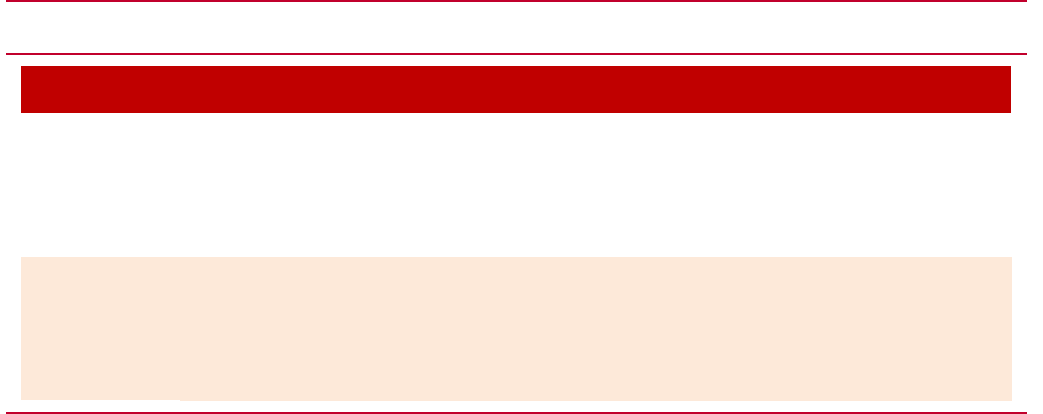






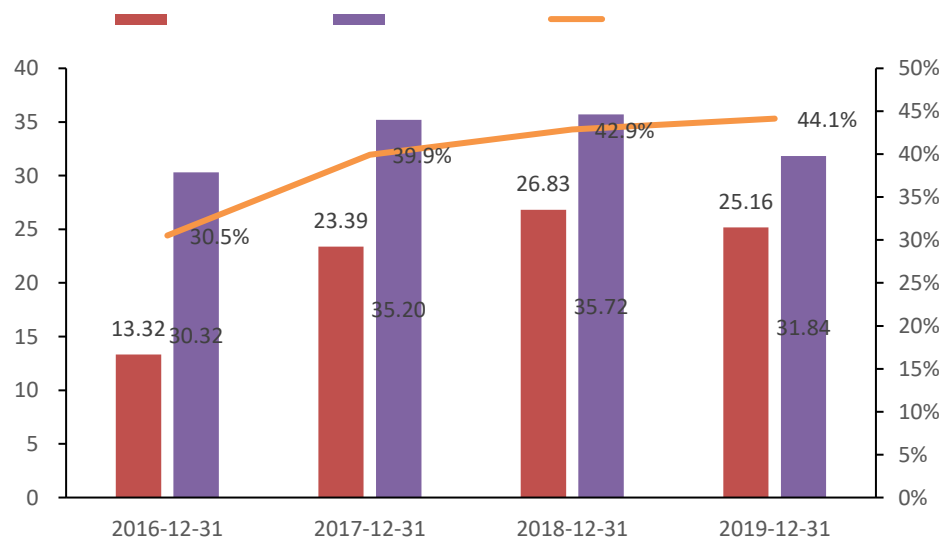
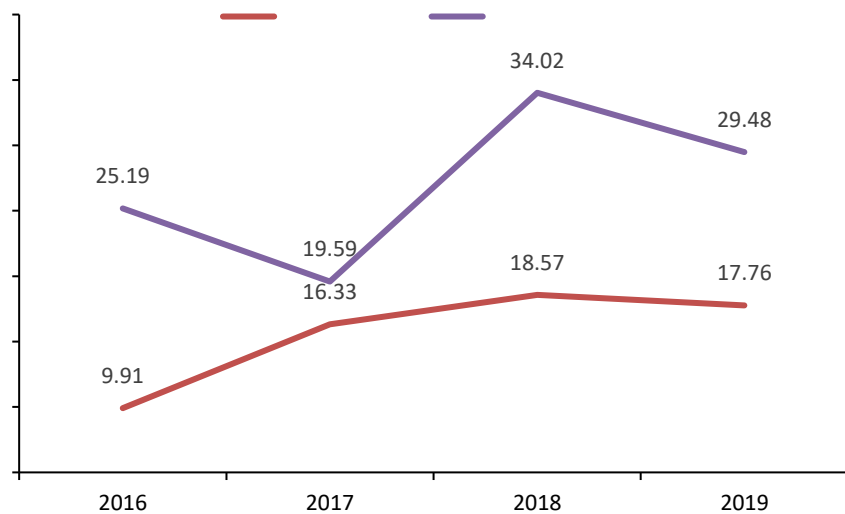
2.3.





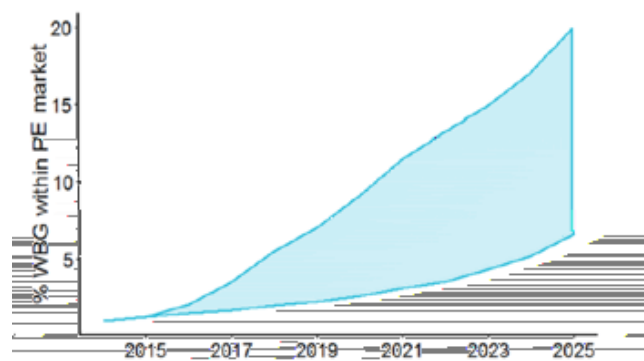
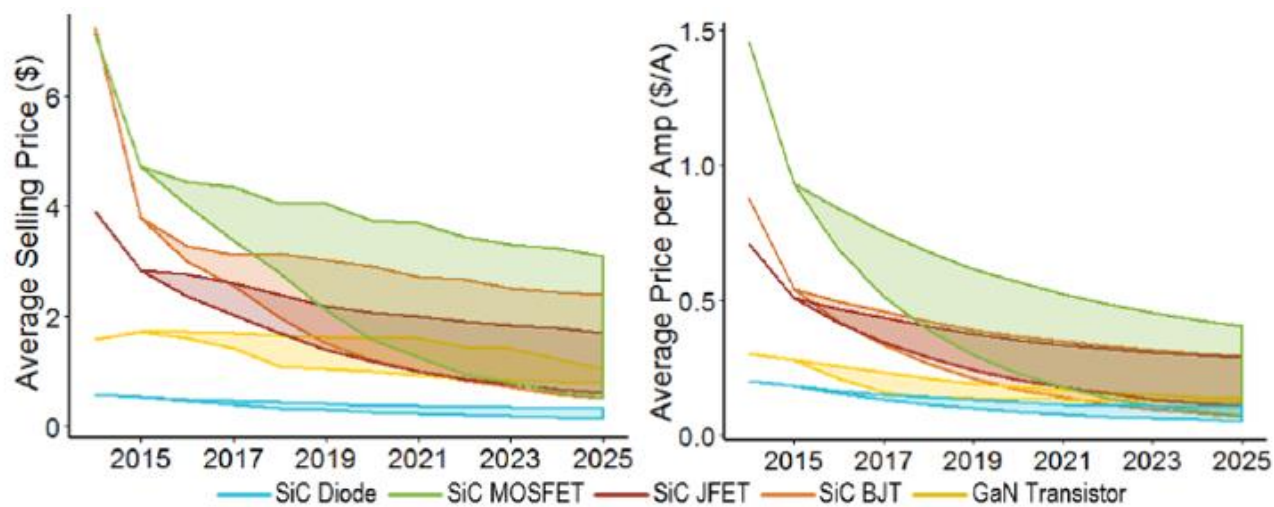
3.

3.1.



3.2.





4.

5.

[Redacted]

[Redacted]